

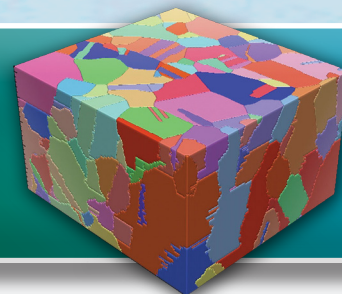


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JANUARY 14, 2019**

5TH WORLD CONGRESS ON INTEGRATED COMPUTATIONAL MATERIALS ENGINEERING (ICME 2019)

July 21–25, 2019 • JW Marriott Indianapolis • Indianapolis, Indiana, USA



Presenting your research at ICME 2019 offers high visibility and recognition of your contributions to the field. ICME 2019 is the only conference dedicated to bringing stakeholders from across nations, disciplines, and organizations to focus on integration priorities and gaps that need to be addressed in order to advance the field.

Don't miss this opportunity to share your work and connect with leaders in ICME.

This congress will provide a forum for presentations and discussions centering on ICME-related topics, including but not limited to:

- The wide range of materials programs where an ICME approach validated by experimental efforts is applicable, including computational- and experimental-based talks
- Individual computational methods utilized in an ICME approach, including both advantages and limitations
- High-throughput computing application in ICME
- Development of materials processing and materials characterization technology
- Incorporation of “big data, data fusion, and machine learning” for materials and product development with ICME methodologies
- Bridging the gap of across-scale materials simulation
- Success stories of ICME on materials development
- ICME implementation strategies

Attendees are encouraged to submit their work to the TMS journals *Integrating Materials and Manufacturing Innovation*, *JOM*, and *Metallurgical and Materials Transactions A*, which will be publishing topical collections on ICME. These collections will take the place of a traditional conference proceedings publication.

Learn more about publishing options and technical topics planned for this congress at www.tms.org/ICME2019.

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